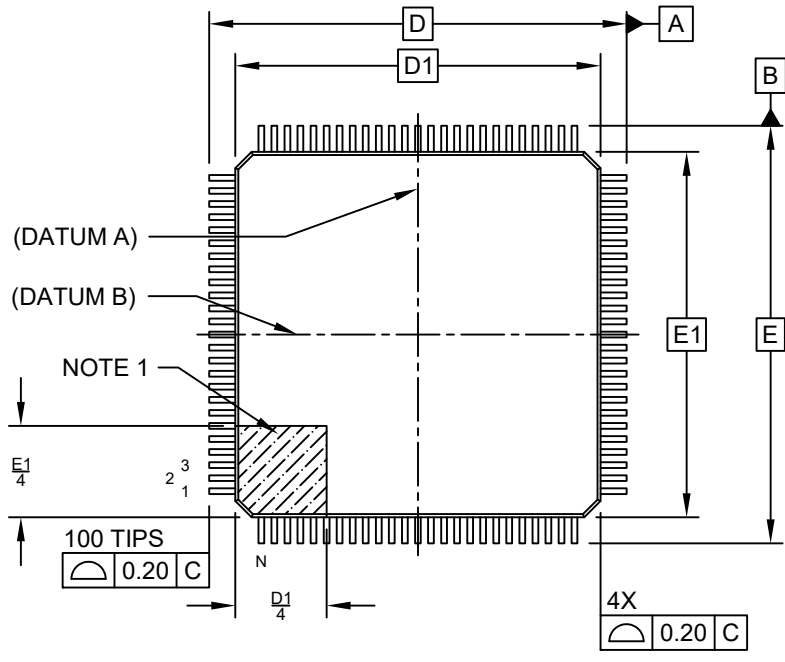
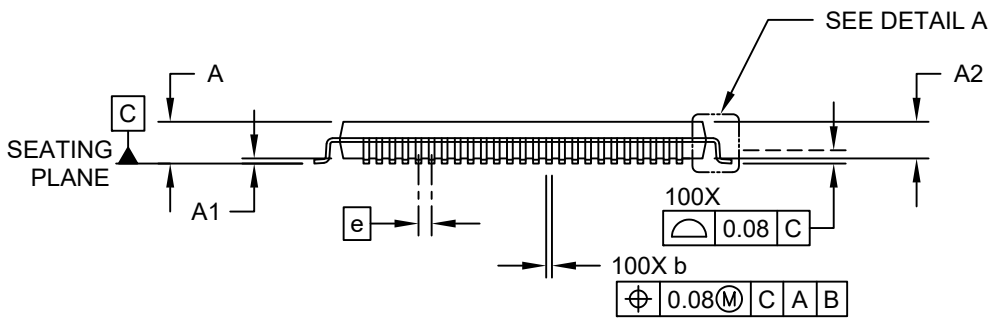


100-Lead Low Profile Quad Flatpack (PL) - 14x14 mm Body [LQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



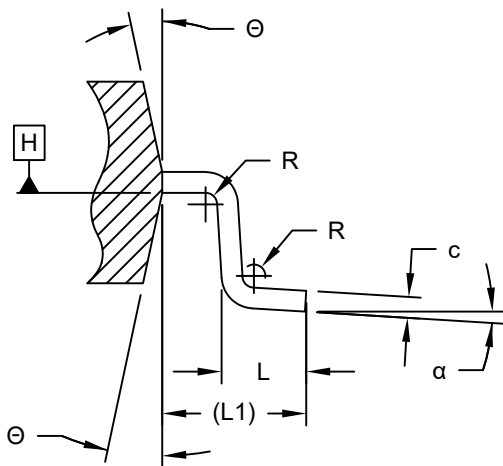
TOP VIEW



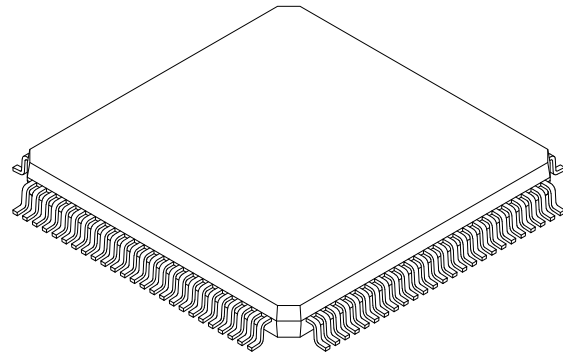
SIDE VIEW

100-Lead Low Profile Quad Flatpack (PL) - 14x14 mm Body [LQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



DETAIL A



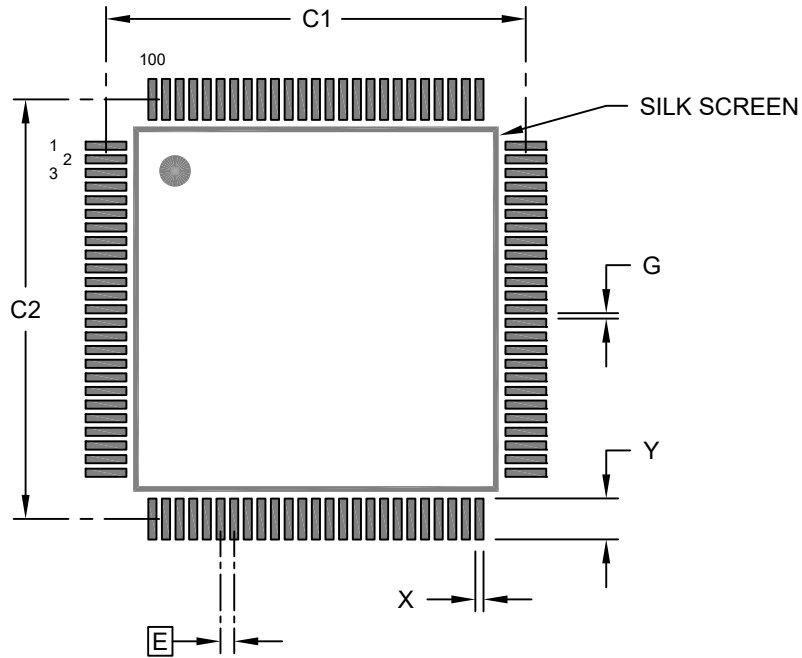
| Dimension Limits | Units | MILLIMETERS | | |
|--------------------------|-------|-------------|------|------|
| | | MIN | NOM | MAX |
| Number of Leads | N | 100 | | |
| Pitch | e | 0.50 BSC | | |
| Overall Height | A | - | - | 1.60 |
| Standoff | A1 | 0.05 | - | 0.15 |
| Molded Package Thickness | A2 | 1.35 | - | 1.45 |
| Overall Length | D | 16.00 BSC | | |
| Molded Package Length | D1 | 14.00 BSC | | |
| Overall Width | E | 16.00 BSC | | |
| Molded Package Width | E1 | 14.00 BSC | | |
| Lead Width | b | 0.17 | 0.22 | 0.27 |
| Lead Thickness | c | 0.09 | - | 0.20 |
| Lead Length | L | 0.45 | 0.60 | 0.75 |
| Footprint | (L1) | 1.00 REF | | |
| Mold Draft Angle | Θ | 11° | 12° | 13° |
| Lead Angle | α | 0° | 3.5° | 7° |
| Bend Radius | R | 0.08 | - | - |

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Package is saw singulated
- Dimensioning and tolerancing per ASME Y14.5M
 - BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 - REF: Reference Dimension, usually without tolerance, for information purposes only.

100-Lead Low Profile Quad Flatpack (PL) - 14x14 mm Body [LQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

| Dimension Limits | Units | MILLIMETERS | | |
|---------------------------|-------|-------------|-------|------|
| | | MIN | NOM | MAX |
| Contact Pitch | E | 0.50 BSC | | |
| Contact Pad Spacing | C1 | | 15.40 | |
| Contact Pad Spacing | C2 | | 15.40 | |
| Contact Pad Width (X100) | X | | | 0.30 |
| Contact Pad Length (X100) | Y | | | 1.50 |
| Space Between Pads | G | 0.20 | | |

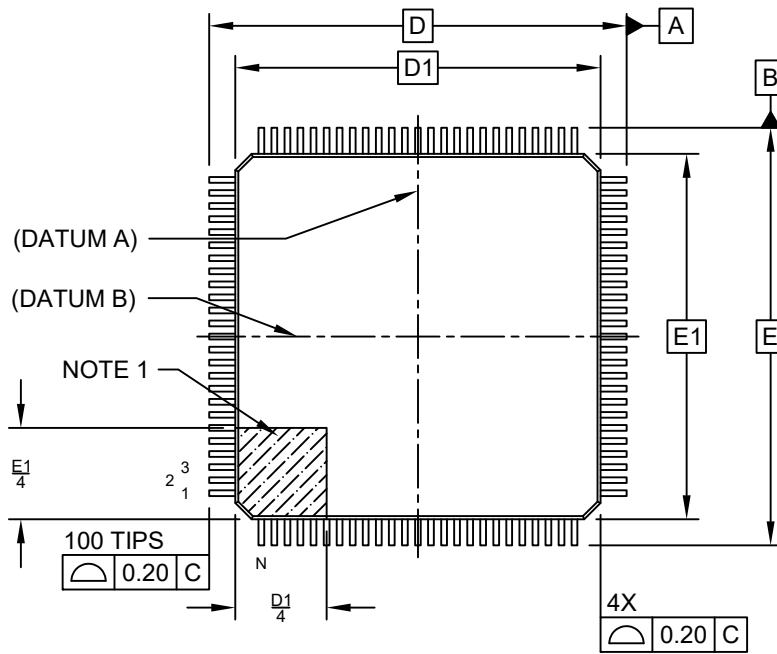
Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

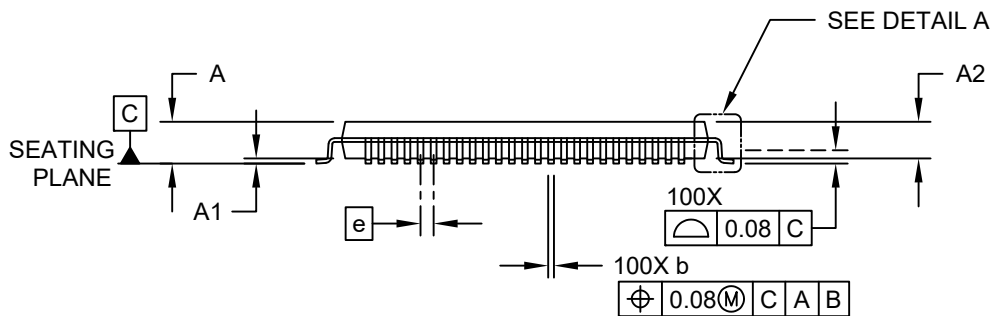
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

100-Lead Low Profile Quad Flatpack (H7X) - 14x14 mm Body [LQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



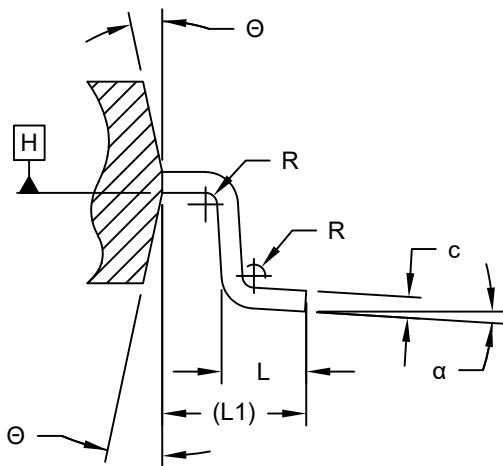
TOP VIEW



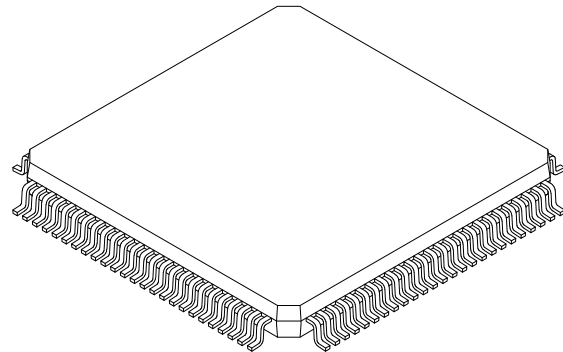
SIDE VIEW

100-Lead Low Profile Quad Flatpack (H7X) - 14x14 mm Body [LQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



DETAIL A



| Dimension Limits | Units | MILLIMETERS | | |
|--------------------------|----------|-------------|------|------|
| | | MIN | NOM | MAX |
| Number of Leads | N | 100 | | |
| Pitch | e | 0.50 BSC | | |
| Overall Height | A | - | - | 1.60 |
| Standoff | A1 | 0.05 | - | 0.15 |
| Molded Package Thickness | A2 | 1.35 | - | 1.45 |
| Overall Length | D | 16.00 BSC | | |
| Molded Package Length | D1 | 14.00 BSC | | |
| Overall Width | E | 16.00 BSC | | |
| Molded Package Width | E1 | 14.00 BSC | | |
| Lead Width | b | 0.17 | 0.22 | 0.27 |
| Lead Thickness | c | 0.09 | - | 0.20 |
| Lead Length | L | 0.45 | 0.60 | 0.75 |
| Footprint | (L1) | 1.00 REF | | |
| Mold Draft Angle | Θ | 11° | 12° | 13° |
| Lead Angle | α | 0° | 3.5° | 7° |
| Bend Radius | R | 0.08 | - | - |

Notes:

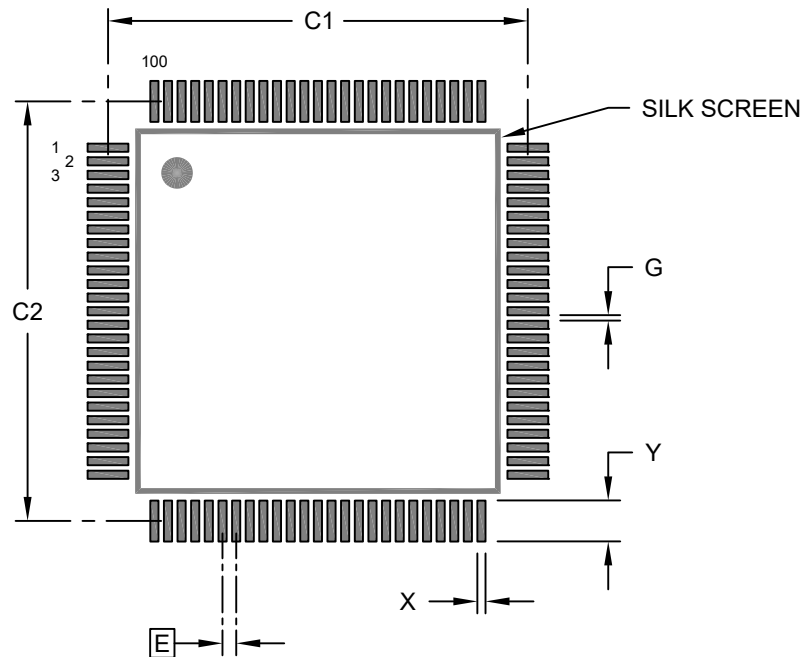
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated
3. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

100-Lead Low Profile Quad Flatpack (H7X) - 14x14 mm Body [LQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

| Dimension Limits | Units | MILLIMETERS | | |
|---------------------------|-------|-------------|-------|------|
| | | MIN | NOM | MAX |
| Contact Pitch | E | 0.50 BSC | | |
| Contact Pad Spacing | C1 | | 15.40 | |
| Contact Pad Spacing | C2 | | 15.40 | |
| Contact Pad Width (X100) | X | | | 0.30 |
| Contact Pad Length (X100) | Y | | | 1.50 |
| Space Between Pads | G | 0.20 | | |

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.